

Product / Process Change Notice

Parts Affected:

Chip process CPD66X, switching diodes, wafers and bare die

Extent of Change:

The CPD66X has been modified from an Sb (antimony) dopant to an As (arsenic) dopant. There are no resultant physical changes to die size or metallization.

Reason for Change:

The dopant material was changed in order to enhance typical forward voltage (V_F) performance and, hence, reduce forward conduction losses.

Effect of Change:

The wafer process meets all electrical specifications of the individual devices listed on the following page.

Qualification:

P/N: CPD66X Process using As

Package: SOD-123

No.	Test	Conditions (Reference standards are in bold)	Qty	Pass/Fail	Test Results
1	Device Life Tests				
a	High Temperature Reverse Bias (HTRB)	T=125°C, t = 1000 hours Bias conditions per device datasheet JESD22-A108	77	Pass	77/77
b	Intermittent Operational Load Life	T=125°C, t = 1000 hours JESD22-A108	22	Pass	22/22

Effective Date of Change:

Effective Immediately.

Sample Availability:

Please contact your salesperson or manufacturer's representative for samples.

PCN #176
Notification Date:
August 27, 2019

Part Numbers Affected:

CBAS17	CEN1221
CEN1230	CEN1235
CEN1344	CMDD3003
CMHD3595	CMHD457A
CMHD459A	CMKD3003DO
CMLD3003DO	CMLD3003DOG
CMOD3003	CMOD3003G
CMPD3003	CMPD3003A
CMPD3003C	CMPD3003S
CMXD3003TO	CPD66X-CLL459A-WN
CPD66X-CMHD459A-WN	CPD66X-CMPD3003-CT
CPD66X-CMPD3003-WN	CPD66X-1N3595-WN
CPD66X-1N3595-WR	CPD66X-1N457A-CT
CPD66X-1N457A-WN	CPD66X-1N485B-CT
CPD66X-1N485B-WN	



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As per JEDEC standard JESD46, Customer Notification of Product/Process Changes by Solid-State Suppliers, a lack of acknowledgement of a PCN within thirty (30) days constitutes acceptance of the change.

The undersigned acknowledges and accepts Central Semiconductor's Product/Process Change Notification (PCN).

Company Name:	
Address:	
Printed Name:	
Title:	
Signature:	
Date:	